CLAIMS

1. A resin composition comprising at least one polymer compound selected from the group consisting of polyamide, polyimide, polyamideimide and polybenzoxazole as a component (A), a cationic polymerizable compound as a component (B), and a photocationic polymerization initiator as a component (C), wherein

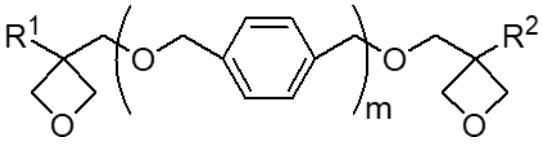
the component (B) contains both an epoxy compound as a component (B1) and an oxetane compound as a component (B2) and

the resin composition is a negative photosensitive resin composition.

2. The resin composition according to claim 1, wherein the total of the component (B2) is 10 to 200 parts by mass when the total of the component (B1) is 100 parts by mass.

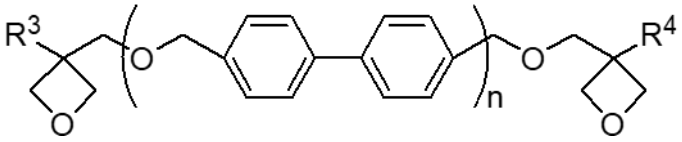
3. The resin composition according to claim 1, wherein the component (B2) contains an oxetane compound having two or more oxetanyl groups in one molecule.

4. The resin composition according to claim 1, wherein the component (B2) contains an oxetane compound represented by the general formula (5) or the general formula (6):



(5)

wherein, in the general formula (5), m is an integer of 1 to 6, and R^1 and R^2 are monovalent organic groups,

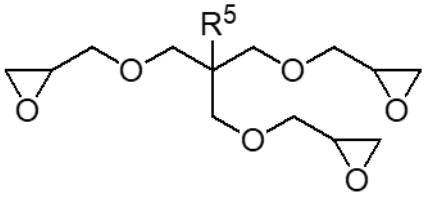


(6)

wherein, in the general formula (6), n is an integer of 1 to 6, and R^3 and R^4 are monovalent organic groups.

5. The resin composition according to claim 1, wherein the component (B1) contains an epoxy compound represented by the general formula (3):

[Chemical Formula 3]

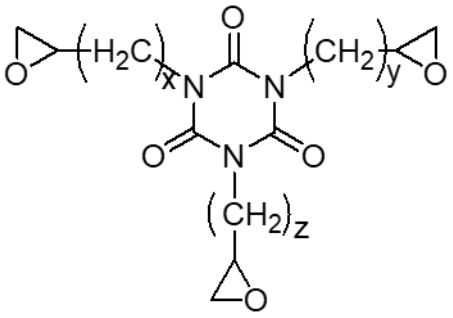


(3)

wherein, in the general formula (3), R^5 is a monovalent organic group.

6. The resin composition according to claim 1, wherein the component (B1) contains an epoxy compound represented by the general formula (4):

[Chemical Formula 4]



(4)

wherein, in the general formula (4), x, y and z each independently represent an integer of 1 to 6.

7. The resin composition according to claim 1, wherein the total of the component (B) is 50 to 200 parts by mass when the total of the component (A) is 100 parts by mass.

8. The resin composition according to claim 1, wherein the component (C) is an onium salt-based photoacid generator.

9. A resin composition film comprising a resin composition coating film and a support, wherein the resin composition coating film is made of the resin composition according to claim 1.

10. A semiconductor device comprising a cured film formed by curing the resin composition according to claim 1.

11. The semiconductor device according to claim 10,

wherein the cured film has a thickness of 40 to 300 μm and the cured film has an aspect ratio of 4 to 20.

12. The semiconductor device according to claim 10, wherein the semiconductor device is an inductor comprising an insulating film and a coil, and the cured film formed by curing the resin composition is used as the insulating film of the inductor.

13. The semiconductor device according to claim 12, wherein the semiconductor device is an inductor comprising an insulating film and a coil formed on a substrate, the semiconductor device further comprising a resin layer between the insulating film and the substrate.

14. The semiconductor device according to claim 13, wherein the resin layer contains at least one polymer compound selected from the group consisting of polyamide, polyimide, polyamideimide and polybenzoxazole, and the content of the polymer compound in the resin layer is 1 to 45% by mass.